

Data Sheet

LC²MOS Quad SPST Switches

ADG441/ADG442/ADG444

FEATURES

44 V supply maximum ratings V_{SS} to V_{DD} analog signal range Low on resistance (<70 Ω) Low ΔR_{ON} (9 Ω max) Low R_{ON} match (3 Ω max) Low power dissipation Fast switching times t_{ON} < 110 ns

 $t_{ON} < 110 \text{ ns}$ $t_{OFF} < 60 \text{ ns}$

Low leakage currents (3 nA max)
Low charge injection (6 pC max)
Break-before-make switching action
Latch-up proof A grade
Plug-in upgrade for DG201A/ADG201A, DG202A/ADG202A,
DG211/ADG211A
Plug-in replacement for DG441/DG442/DG444

APPLICATIONS

Audio and video switching Automatic test equipment Precision data acquisition Battery-powered systems Sample-and-hold systems Communication systems

GENERAL DESCRIPTION

The ADG441, ADG442, and ADG444 are monolithic CMOS devices that comprise of four independently selectable switches. They are designed on an enhanced LC²MOS process that provides low power dissipation yet gives high switching speed and low on resistance.

The on resistance profile is very flat over the full analog input range, which ensures good linearity and low distortion when switching audio signals. High switching speed also makes the parts suitable for video signal switching. CMOS construction ensures ultralow power dissipation, making the parts ideally suited for portable and battery-powered instruments. The ADG441, ADG442, and ADG444 contain four independent SPST switches. Each switch of the ADG441 and ADG444 turns on when a logic low is applied to the appropriate control input. The ADG442 switches are turned on with logic high on the appropriate control input. The ADG441 and ADG444 switches differ in that the ADG444 requires a 5 V logic power supply that is applied to the $V_{\rm L}$ pin. The ADG441 and ADG442 do not have a $V_{\rm L}$ pin, the logic power supply is generated internally by an on-chip voltage generator.

Rev. B

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FUNCTIONAL BLOCK DIAGRAM

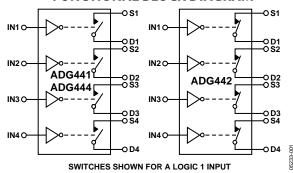


Figure 1.

Each switch conducts equally well in both directions when ON and has an input signal range that extends to the power supplies. In the OFF condition, signal levels up to the supplies are blocked. All switches exhibit break-before-make switching action for use in multiplexer applications. Inherent in the design is the low charge injection for minimum transients when switching the digital inputs.

PRODUCT HIGHLIGHTS

- Extended signal range. The ADG441A/ADG442A/ ADG444A are fabricated on an enhanced LC²MOS, trench-isolated process, giving an increased signal range that extends to the supply rails.
- 2. Low power dissipation.
- 3. Low Ron.
- 4. Trench isolation guards against latch-up for A grade parts. A dielectric trench separates the P and N channel transistors thereby preventing latch-up even under severe overvoltage conditions.
- Break-before-make switching. This prevents channel shorting when the switches are configured as a multiplexer.
- Single-supply operation. For applications where the analog signal is unipolar, the ADG441/ADG442/ADG444 can be operated from a single-rail power supply. The parts are fully specified with a single 12 V power supply.

Data Sheet

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5/05—Rev. 0 to Rev. A	
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SPECIFICATIONS

DUAL SUPPLY¹

 V_{DD} = +15 V ± 10%, V_{SS} = -15 V ± 10%, V_{L} = +5 V ± 10% (ADG444), GND = 0 V, unless otherwise noted.

Table 1.

	B Version				
Parameter	+25°C	-40°C to +85°C	Unit	Test Conditions/Comments	
ANALOG SWITCH					
Analog Signal Range		V_{SS} to V_{DD}	V		
Ron	40		Ω typ	$V_D = \pm 8.5 \text{V}, I_S = -10 \text{mA}$	
	70	85	Ω max	$V_{DD} = +13.5 \text{ V}, V_{SS} = -13.5 \text{ V}$	
ΔRon		4	Ω typ	$-8.5 \text{ V} \le \text{V}_{D} \le +8.5 \text{ V}$	
		9	Ω max		
Ron Match		1	Ω typ	$V_D = 0 \text{ V, } I_S = -10 \text{ mA}$	
		3	Ω max		
LEAKAGE CURRENTS				$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$	
Source OFF Leakage I _s (OFF)	±0.01		nA typ	$V_D = \pm 15.5 \text{ V}, V_S = \mp 15.5 \text{ V}$	
	±0.5	±3	nA max	See Figure 15	
Drain OFF Leakage I _D (OFF)	±0.01	±3	nA typ		
Drain of Fedinage is (OTT)		. •		$V_D = \pm 15.5 \text{ V}, V_S = \mp 15.5 \text{ V}$	
	±0.5	±3	nA max	See Figure 15	
Channel ON Leakage I _D , I _S (ON)	±0.08	. •	nA typ	$V_S = V_D = \pm 15.5 \text{ V}$	
	±0.5	±3	nA max	See Figure 16	
DIGITAL INPUTS					
Input High Voltage, V _{INH}		2.4	V min		
Input Low Voltage, V _{INL}		0.8	V max		
Input Current					
linl or linh		±0.00001	μA typ	$V_{IN} = V_{INL} \text{ or } V_{INH}$	
		±0.5	μA max		
DYNAMIC CHARACTERISTICS ²					
ton	85		ns typ	$R_L = 1 \text{ k}\Omega$, $C_L = 35 \text{ pF}$;	
	110	170	ns max	$V_S = \pm 10 \text{ V}$; see Figure 17	
toff	45		ns typ	$R_L = 1 \text{ k}\Omega$, $C_L = 35 \text{ pF}$;	
	60	80	ns max	$V_S = \pm 10 \text{ V}$; see Figure 17	
t _{open}	30		ns typ	$R_L = 1 \text{ k}\Omega$, $C_L = 35 \text{ pF}$;	
Charge Injection	1		pC typ	$V_S = 0 \text{ V}, R_S = 0 \Omega, C_L = 1 \text{ nF};$	
	6		pC max	$V_{DD} = +15 \text{ V}, V_{SS} = -15 \text{ V}; \text{ see Figure 18}$	
OFF Isolation	60		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$; $f = 1 MHz$; see Figure 19	
Channel-to-Channel Crosstalk	100		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$; $f = 1 MHz$; see Figure 20	
Cs (OFF)	4		pF typ	f = 1 MHz	
C _D (OFF)	4		pF typ	f = 1 MHz	
C_D , C_S (ON)	16		pF typ	f = 1 MHz	
POWER REQUIREMENTS				$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$	
I _{DD}				Digital Inputs = 0 V or 5 V	
ADG441/ADG442		80	μA max		
ADG444	0.001		μA typ		
	1	2.5	μA max		
Iss	0.0001		μA typ		
	1	2.5	μA max		
I∟ (ADG444 Only)	0.001		μA typ	$V_L = 5.5 \text{ V}$	
•	1	2.5	μA max		

 $^{^{1}}$ Temperature range is: B Version: -40° C to $+85^{\circ}$ C.

² Guaranteed by design, not subject to production test.

SINGLE SUPPLY¹

 V_{DD} = +12 V \pm 10%, V_{SS} = 0 V, V_{L} = +5 V \pm 10% (ADG444), GND = 0 V, unless otherwise noted.

· ·	B Version			
Parameter	+25°C	-40°C to +85°C	Unit	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		0 to V_{DD}	V	
Ron	70		Ωtyp	$V_D = +3 V_1 + 8 V_2 I_S = -5 \text{ mA}$
	110	130	Ω max	$V_{DD} = 10.8 \text{ V}$
ΔRon		4	Ωtyp	$3 \text{ V} \leq \text{V}_D \leq 8 \text{ V}$
		9	Ω max	
R _{ON} Match		1	Ωtyp	$V_D = +6 \text{ V}, I_S = -5 \text{ mA}$
		3	Ω max	
LEAKAGE CURRENT				$V_{DD} = 13.2 \text{ V}$
Source OFF Leakage Is (OFF)	±0.01		nA typ	$V_D = 12.2 \text{ V/1 V}, V_S = 1 \text{ V/12.2 V}$
	±0.5	±3	nA max	See Figure 15
Drain OFF Leakage I _D (OFF)	±0.01		nA typ	$V_D = 12.2 \text{ V/1 V}, V_S = 1 \text{ V/12.2 V}$
2.a 2	±0.5	±3	nA max	See Figure 15
Channel ON Leakage ID, Is (ON)	±0.08		nA typ	$V_S = V_D = 12.2 \text{ V/1 V}$
charmer on Zealage 15/13 (OT)	±0.5	±3	nA max	Figure 16
DIGITAL INPUTS				I i gaile i e
Input High Voltage, V _{INH}		2.4	V min	
Input Low Voltage, VINL		0.8	V max	
Input Current		0.0	Villax	
lint or linh		±0.00001	μA typ	$V_{IN} = V_{INL}$ or V_{INH}
TINE OF TINE		±0.5	μA max	VIN — VINL OI VINN
DYNAMIC CHARACTERISTICS ²			par t t t tart	
ton	105		ns typ	$R_L = 1 \text{ k}\Omega$, $C_L = 35 \text{ pF}$
CON	150	220	ns max	$V_s = 8 \text{ V}$; Figure 17
toff	40	220	ns typ	$R_L = 1 \text{ k}\Omega$, $C_L = 35 \text{ pF}$
COFF	60	100	ns max	$V_s = 8 \text{ V}$; Figure 17
topen	50	100	ns typ	$R_L = 1 \text{ k}\Omega$, $C_L = 35 \text{ pF}$
Charge Injection	2		pC typ	$V_S = 6 \text{ V}, R_S = 0 \Omega, C_L = 1 \text{ nF}$
charge injection	6		pC max	$V_{DD} = 12 \text{ V}, V_{SS} = 0 \text{ V}; \text{ see Figure 18}$
OFF Isolation	60		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 19
Channel-to-Channel Crosstalk	100		dB typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 20
C _s (OFF)	7		pF typ	f = 1 MHz
C _D (OFF)	10		pF typ	f = 1 MHz
C _D , C _s (ON)	16		pF typ	f = 1 MHz
POWER REQUIREMENTS	10		י יאָף	V _{DD} = 13.2 V
I _{DD}				Digital Inputs = 0 V or 5 V
ADG441/ADG442		80	μA max	
ADG4417ADG442 ADG444	0.001	UU	μΑ max μΑ typ	
ADUTTT	1	2.5		
L (ADG444 Only)	0.001	2.5	μA max	V = 55V
I∟ (ADG444 Only)		2.5	μA typ	$V_L = 5.5 \text{ V}$
	1	2.5	μA max	

 $^{^1}$ Temperature range is: B Version: -40°C to $+85^\circ\text{C}.$ 2 Guaranteed by design, not subject to production test.

ABSOLUTE MAXIMUM RATINGS

 $T_A = 25$ °C unless otherwise noted.

Table 3

Table 3.		
Parameter	Rating	
V _{DD} to V _{SS}	44 V	
V _{DD} to GND	-0.3 V to +25 V	
V _{SS} to GND	+0.3 V to -25 V	
V _L to GND	-0.3 V to $V_{DD} + 0.3 \text{ V}$	
Analog, Digital Inputs	V _{SS} – 2 V to V _{DD} + 2 V or 30 mA, Whichever Occurs First	
Continuous Current, S or D	30 mA	
Peak Current, S or D (Pulsed at 1 ms, 10% Duty Cycle Max)	100 mA	
· ·		
Operating Temperature Range		
Industrial (B Version)	–40°C to +85°C	
Storage Temperature Range	−65°C to +150°C	
Junction Temperature	150°C	
Lead Temperature, Soldering (10 sec)	300°C	
Plastic Package, Power Dissipation	470 mW	
$\theta_{ exttt{JA}}$, Thermal Impedance	177°C/W	
Lead Temperature, Soldering (10 sec)	260°C	
SOIC Package, Power Dissipation	600 mW	
$\theta_{ exttt{JA}}$, Thermal Impedance	77°C/W	
Lead Temperature, Soldering		
Vapor Phase (60 sec)	215°C	
Infrared (15 sec)	220°C	

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 4. Truth Table

ADG441/ADG444 IN	ADG442 IN	Switch Condition
0	1	ON
1	0	OFF

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

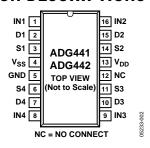


Figure 2. ADG441/ADG442 (DIP/SOIC)

Table 5. ADG441/ADG442 Pin Function Descriptions

Two trials of the first time to the first time time to the first time time time time time time time tim				
Pin No.	Mnemonic	Description		
1, 8, 9, 16	IN1 to IN4	Logic Control Input.		
2, 7, 10, 15	D1 to D4	Drain Terminal. May be an input or output.		
3, 6, 11, 14	S1 to S4	Source Terminal. May be an input or output.		
4	V _{SS}	Most Negative Power Supply Potential in Dual Supplies. In single-supply applications, it may be connected to ground.		
5	GND	Ground (0 V) Reference.		
12	NC	No Connect.		
13	V_{DD}	Most Positive Power Supply Potential.		

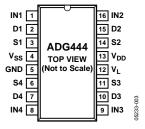


Figure 3. ADG444 (DIP/SOIC)

Table 6. ADG444 Pin Function Descriptions

Pin No.	Mnemonic	Description
1, 8, 9, 16	IN1 to IN4	Logic Control Input.
2, 7, 10, 15	D1 to D4	Drain Terminal. May be an input or output.
3, 6, 11, 14	S1 to S4	Source Terminal. May be an input or output.
4	V _{SS}	Most Negative Power Supply Potential in Dual Supplies. In single-supply applications, it may be connected to ground.
5	GND	Ground (0 V) Reference.
12	VL	Logic Power Supply (5 V).
13	V_{DD}	Most Positive Power Supply Potential.

TYPICAL PERFORMANCE CHARACTERISTICS

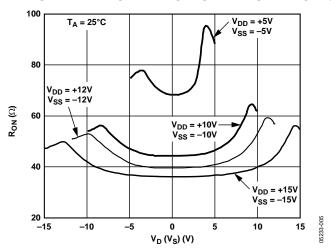


Figure 4. R_{ON} as a Function of V_D (V_S): Dual Supply

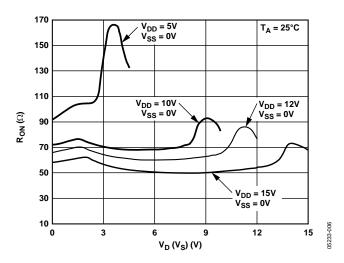


Figure 5. R_{ON} as a Function of V_D (V_S): Single Supply

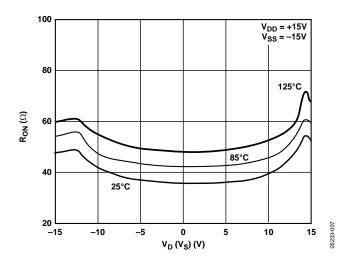


Figure 6. R_{ON} as a Function of V_D (V_S) for Different Temperatures

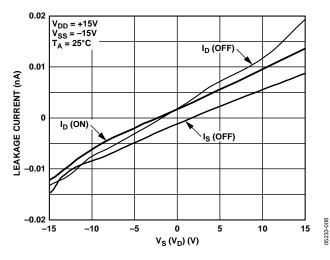


Figure 7. Leakage Currents as a Function of $V_S(V_D)$

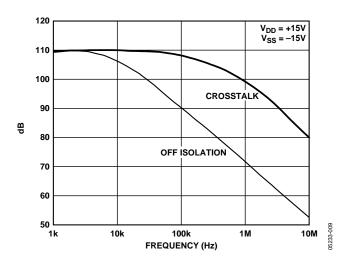


Figure 8. Crosstalk and Off Isolation vs. Frequency

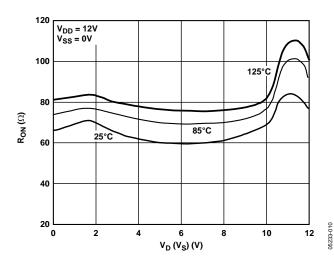


Figure 9. R_{ON} as a Function of V_D (V_S) for Different Temperatures

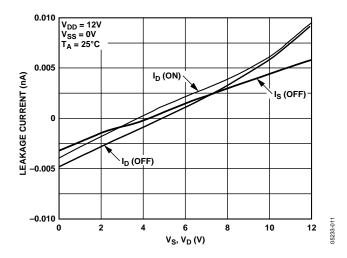


Figure 10. Leakage Currents as a Function of V_S (V_D)

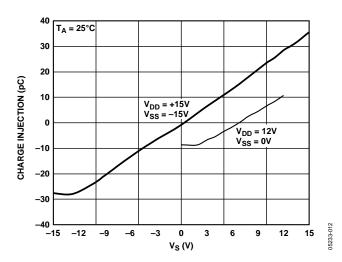


Figure 11. Charge Injection vs. Source Voltage

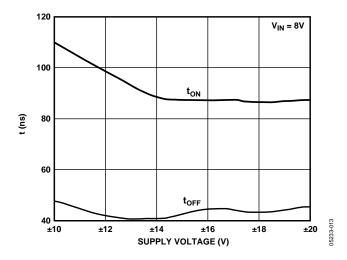


Figure 12. Switching Time vs. Bipolar Supply

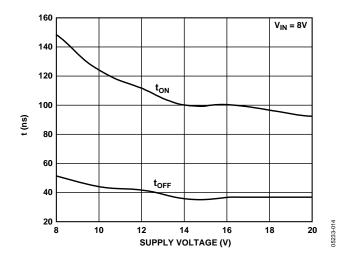
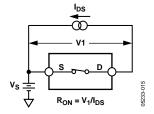
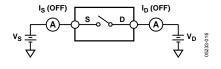


Figure 13. Switching Time vs. Single Supply

TEST CIRCUITS





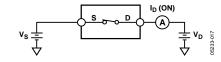


Figure 14. On Resistance

Figure 15. Off Leakage

Figure 16. On Leakage

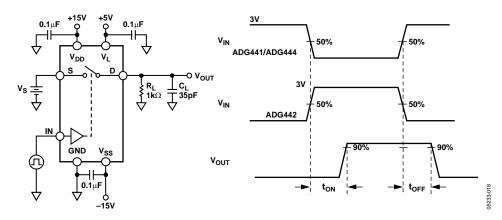


Figure 17. Switching Times

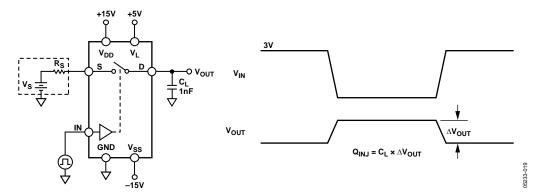


Figure 18. Charge Injection

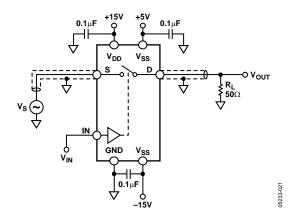


Figure 19. Off Isolation

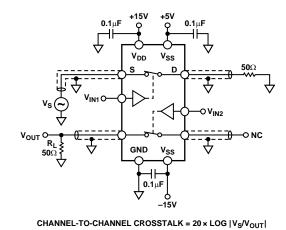


Figure 20. Channel-to-Channel Crosstalk

TERMINOLOGY

Ron

Ohmic resistance between D and S.

Ron Match

Difference between the Ron of any two channels.

Is (OFF)

Source leakage current with the switch OFF.

I_D (OFF)

Drain leakage current with the switch OFF.

 I_D , I_S (ON)

Channel leakage current with the switch ON.

 $V_D(V_S)$

Analog voltage on Terminals D, S.

Cs (OFF)

OFF switch source capacitance.

C_D (OFF)

OFF switch drain capacitance.

CD, Cs (ON)

ON switch capacitance.

 t_{ON}

Delay between applying the digital control input and the output switching on.

toff

Delay between applying the digital control input and the output switching off.

 t_{OPEN}

Break-before-make delay when switches are configured as a multiplexer.

Crosstalk

A measure of unwanted signal which is coupled through from one channel to another as a result of parasitic capacitance.

Off Isolation

A measure of unwanted signal coupling through an OFF switch.

Charge Injection

A measure of the glitch impulse transferred from the digital input to the analog output during switching.

TRENCH ISOLATION

In the ADG441A, ADG442A, and ADG444A, an insulating oxide layer (trench) is placed between the NMOS and the PMOS transistors of each CMOS switch. Parasitic junctions, which occur between the transistors in junction isolated switches, are eliminated, and the result is a completely latch-up proof switch.

In junction isolation, the N and P wells of the PMOS and NMOS transistors form a diode that is reverse-biased under normal operation. However, during overvoltage conditions, this diode becomes forward-biased. A silicon-controlled rectifier (SCR) type circuit is formed by the two transistors causing a significant amplification of the current which, in turn, leads to latch-up. With trench isolation, this diode is removed, and the result is a latch-up proof switch.

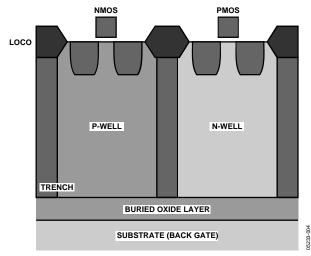
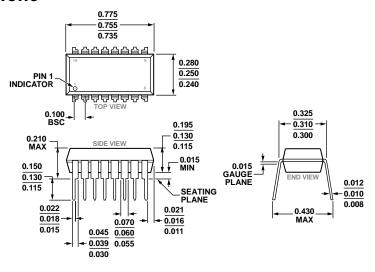


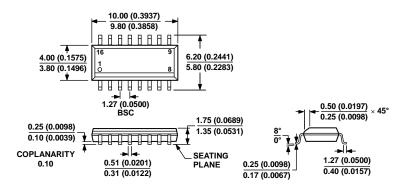
Figure 21. Trench Isolation

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-001-BB

Figure 22. 16-Lead Plastic Dual In-Line Package [PDIP] Narrow Body (N-16) Dimensions shown in inches



COMPLIANT TO JEDEC STANDARDS MS-012-AC

CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 23. 16-Lead Standard Small Outline Package [SOIC_N] (R-16) Dimensions shown in millimeters and (inches)

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ORDERING GUIDE

Model ^{1, 2}	Temperature Range	Package Description	Package Option
ADG441BNZ	-40°C to +85°C	16-Lead Plastic Dual In-Line Package [PDIP]	N-16
ADG441BR	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441BR-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441BRZ	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441BRZ-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441ABCHIPS		DIE	
ADG441ABR-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441ABRZ-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG442BNZ	-40°C to +85°C	16-Lead Plastic Dual In-Line Package [PDIP]	N-16
ADG442BRZ	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG442BRZ-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG444BNZ	−40°C to +85°C	16-Lead Plastic Dual In-Line Package [PDIP]	N-16
ADG444BR	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG444BR-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG444BRZ	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG444BRZ-REEL	−40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16

 $^{^{1}}$ Z = RoHS Compliant Part. 2 A = Trench isolated.

Data Sheet

ADG441/ADG442/ADG444

NOTES

NOTES

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Analog Devices Inc.:

ADG442BNZ ADG442BRZ-REEL ADG442BRZ